



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF  
MANUFACTURING THE PACKAGE

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of one month(s), extending the time for responding to the Office Action of December 7, 2006 to February 7, 2007.

A check for the statutory fee of \$120.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Carl J. Pellegrino 01/09/2007 MAHME1 00000063 10721382  
Registration No. 40,766

120.00 OP

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WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: January 9, 2007